BFP740ESD

SiGe:C NPN RF bipolar transistor

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Product description

The BFP740ESD is a wideband NPN RF heterojunction bipolar transistor (HBT) with an integrated ESD protection.

Feature list

- Unique combination of high end RF performance and robustness:
  21 dBm maximum RF input power, 2 kV ESD robustness (HBM) due to integrated protection circuits
- NF_{min} = 0.65 dB at 2.4 GHz and 0.9 dB at 5.5 GHz, 3 V, 6 mA
- High gain G_{ms} = 25.5 dB at 2.4 GHz and G_{ma} = 18.5 dB at 5.5 GHz, 3 V, 25 mA
- OIP_3 = 22 dBm at 5.5 GHz, 3 V, 25 mA

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Wireless communications: WLAN, WiMax and UWB
- Satellite communication systems: GNSS navigation systems (GPS, GLONASS, BeiDou, Galileo), satellite radio (SDARs, DAB) and C-band LNB
- Multimedia applications such as portable TV, CATV and FM radio
- ISM applications like RKE, AMR and Zigbee, as well as for emerging wireless applications

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin Configuration				Marking	Pieces / Reel
BFP740ESD / BFP740ESDH6327XTSA1	SOT343	1 = B	2 = E	3 = C	4 = E	T7s	3000

***Attention*: ESD (Electrostatic discharge) sensitive device, observe handling precautions**

Table of contents

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at T_A = 25 °C (unless otherwise specified)

Parameter	Symbol	Values		Unit	Note or test condition
		Min.	Max.		
Collector emitter voltage	V_{CEO}	–	4.2	V	Open base
			3.7		T_A = -55 °C, open base
Collector base voltage [1]	V_{CBO}		4.9		Open emitter
			4.4		T_A = -55 °C, open emitter
Collector emitter voltage [2]	V_{CES}		4.2		E-B short circuited
			3.7		T_A = -55 °C, E-B short circuited
Base current [3]	I_B	-10	5	mA	–
Collector current	I_C	–	45		
RF input power	P_{RFin}	–	21	dBm	
ESD stress pulse [4]	V_{ESD}	-2	2	kV	HBM, all pins, acc. to JESD22-A114
Total power dissipation[5]	P_{tot}	–	160	mW	$T_S \leq 98$ °C
Junction temperature	T_J	–	150	°C	–
Storage temperature	T_{Stg}	-55			

Attention**: **Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.

1 Low V_{CBO} due to design.
2 V_{CES} is similar to V_{CEO} due to design.
3 Sustainable reverse bias current is high due to design
4 ESD robustness is high due to design
5 T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Junction - soldering point	R_{thJS}	–	325	–	K/W	–

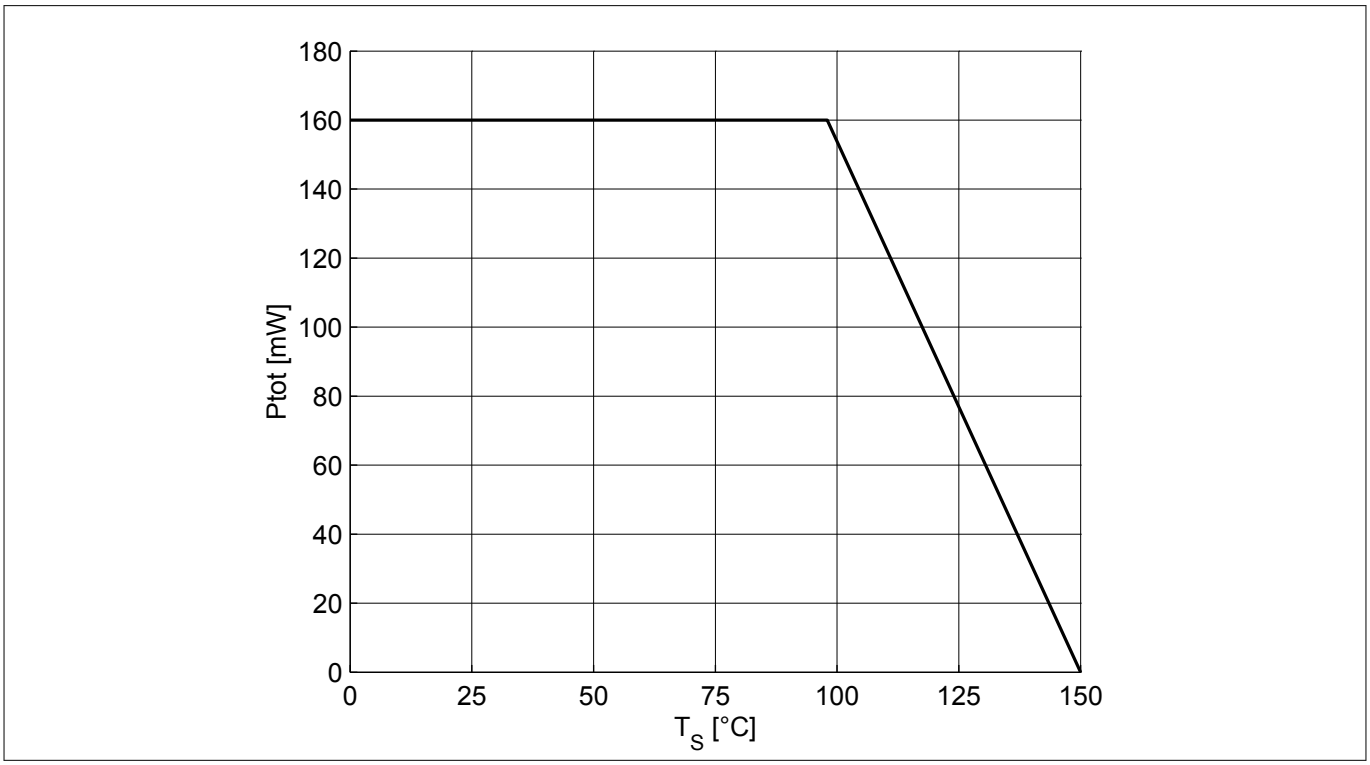

Figure 1 Total power dissipation $P_{tot} = f(T_S)$

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at T_A = 25 °C

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(BR)CEO}$	4.2	4.7	–	V	I_C = 1 mA, I_B = 0, open base
Collector emitter leakage current	I_{CES}	–	–	400 [1)]	nA	V_{CE} = 2 V, V_{BE} = 0, E-B short circuited
Collector base leakage current	I_{CBO}			400 [1)]		V_{CB} = 2 V, I_E = 0, open emitter
Emitter base leakage current	I_{EBO}			10 [1)]	µA	V_{EB} = 0.5 V, I_C = 0, open collector
DC current gain	h_{FE}	160	250	400		V_{CE} = 3 V, I_C = 25 mA, pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at T_A = 25 °C

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Transition frequency	f_T	–	45	–	GHz	V_{CE} = 3 V, I_C = 25 mA, f = 2 GHz
Collector base capacitance	C_{CB}		0.08		pF	V_{CB} = 3 V, V_{BE} = 0, f = 1 MHz, emitter grounded
Collector emitter capacitance	C_{CE}		0.45			V_{CE} = 3 V, V_{BE} = 0, f = 1 MHz, base grounded
Emitter base capacitance	C_{EB}		0.55			V_{EB} = 0.4 V, V_{CB} = 0, f = 1 MHz, collector grounded

1 Maximum values not limited by the device but by the short cycle time of the 100% test

3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, T_A = 25 °C.

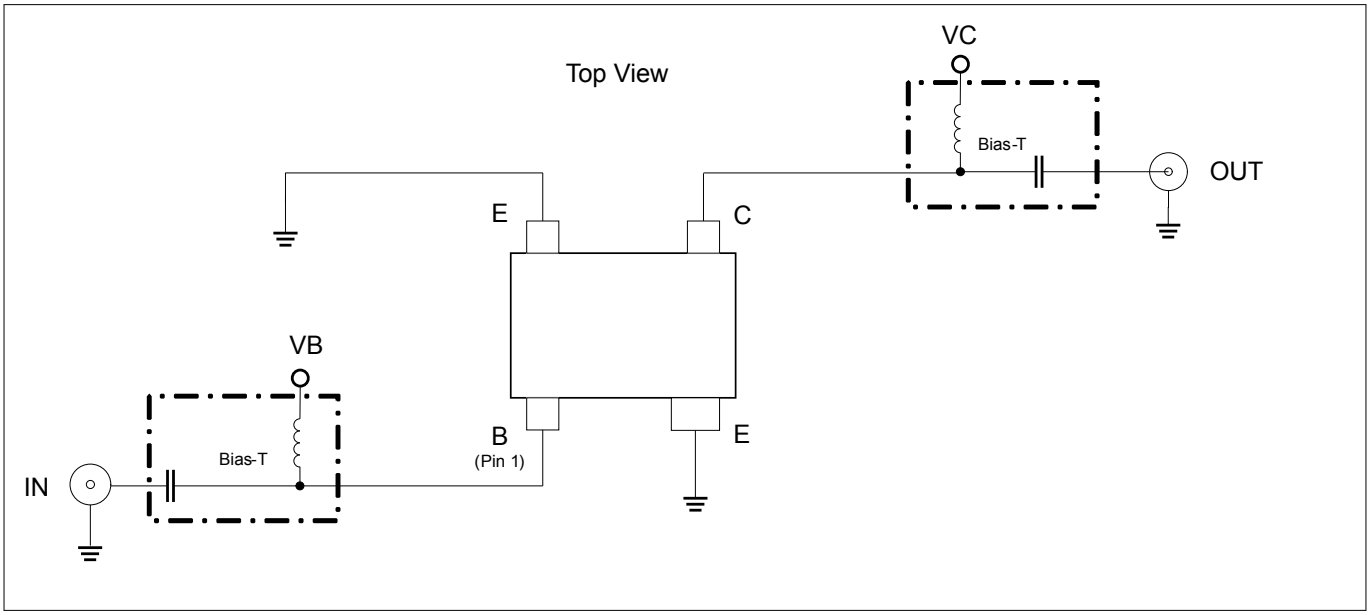

Figure 2 Testing circuit

Table 6 AC characteristics, V_{CE} = 3 V, f = 150 MHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	38.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		34			
Noise figure						
• Minimum noise figure	NF_{min}		0.55			I_C = 6 mA
• Associated gain	G_{ass}		30.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		23.5			
• 1 dB gain compression point at output	OP_{1dB}		9			

Electrical characteristics

Table 7 AC characteristics, V_{CE} = 3 V, f = 450 MHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	33.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		32			
Noise figure						
• Minimum noise figure	NF_{min}		0.55			I_C = 6 mA
• Associated gain	G_{ass}		28.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		23.5			
• 1 dB gain compression point at output	OP_{1dB}		9.5			

Table 8 AC characteristics, V_{CE} = 3 V, f = 900 MHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	30.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		29			
Noise figure						
• Minimum noise figure	NF_{min}		0.55			I_C = 6 mA
• Associated gain	G_{ass}		25.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		24			
• 1 dB gain compression point at output	OP_{1dB}		9.5			

Table 9 AC characteristics, V_{CE} = 3 V, f = 1.5 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	28	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		25.5			
Noise figure						
• Minimum noise figure	NF_{min}		0.6			I_C = 6 mA
• Associated gain	G_{ass}		23			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		24.5			
• 1 dB gain compression point at output	OP_{1dB}		10			

Electrical characteristics

Table 10 AC characteristics, V_{CE} = 3 V, f = 1.9 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	26.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		24			
Noise figure						
• Minimum noise figure	NF_{min}		0.6			I_C = 6 mA
• Associated gain	G_{ass}		21			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		25			
• 1 dB gain compression point at output	OP_{1dB}		10			

Table 11 AC characteristics, V_{CE} = 3 V, f = 2.4 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	25.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		22			
Noise figure						
• Minimum noise figure	NF_{min}		0.65			I_C = 6 mA
• Associated gain	G_{ass}		20			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		25			
• 1 dB gain compression point at output	OP_{1dB}		10.5			

Table 12 AC characteristics, V_{CE} = 3 V, f = 3.5 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	23	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		19			
Noise figure						
• Minimum noise figure	NF_{min}		0.7			I_C = 6 mA
• Associated gain	G_{ass}		16.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		24.5			
• 1 dB gain compression point at output	OP_{1dB}		10.5			

Electrical characteristics

Table 13 AC characteristics, V_{CE} = 3 V, f = 5.5 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	18.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		14.5			
Noise figure						
• Minimum noise figure	NF_{min}		0.9			I_C = 6 mA
• Associated gain	G_{ass}		13.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		22			
• 1 dB gain compression point at output	OP_{1dB}		10			

Table 14 AC characteristics, V_{CE} = 3 V, f = 10 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain					dB	
• Maximum power gain	G_{ms}	–	14.5	–		I_C = 25 mA
• Transducer gain	$\|S_{21}\|^2$		7.5			
Noise figure						
• Minimum noise figure	NF_{min}		1.8			I_C = 6 mA
• Associated gain	G_{ass}		8.5			
Linearity					dBm	$Z_S = Z_L$ = 50 Ω, I_C = 25 mA
• 3rd order intercept point at output	OIP_3		21			
• 1 dB gain compression point at output	OP_{1dB}		7.5			

Note: $G_{ms} = |S_{21} / S_{12}|$ for $k < 1$; $G_{ma} = |S_{21} / S_{12}|(k-(k^2-1)^{1/2})$ for $k > 1$. In order to get the NF_{min} values stated in this chapter the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.2 MHz to 12 GHz.

3.4 Characteristic DC diagrams

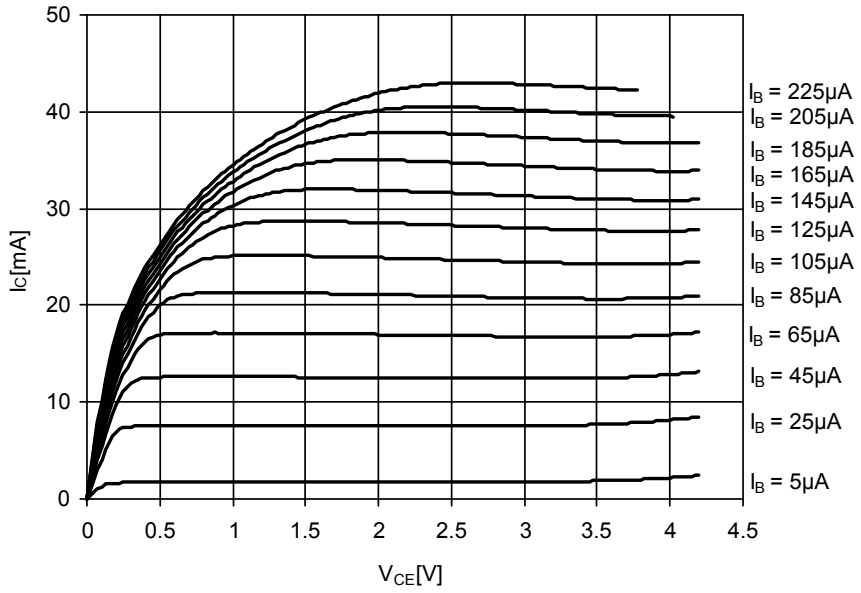

Figure 3 **Collector current vs. collector emitter voltage $I_C = f(V_{CE})$, I_B = parameter**

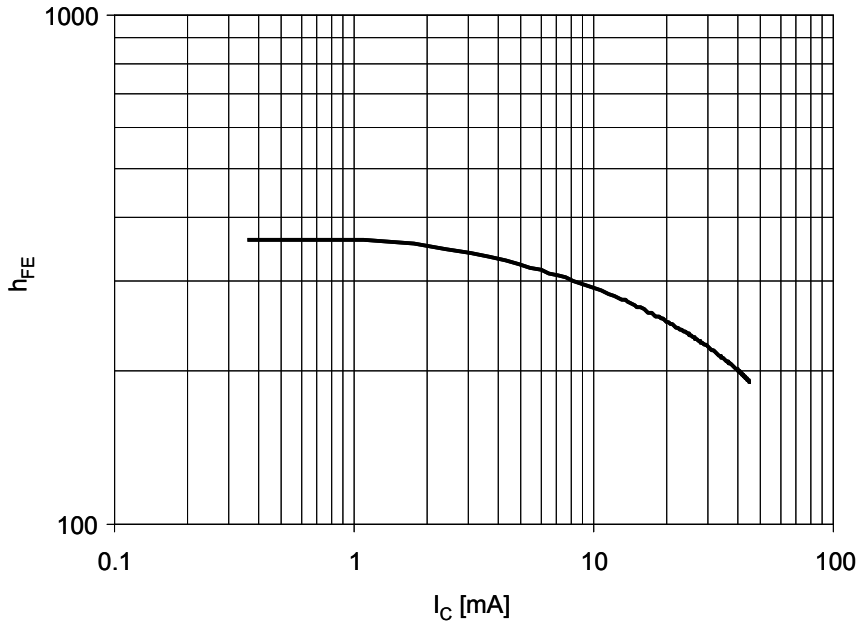

Figure 4 **DC current gain $h_{FE} = f(I_C)$, V_{CE} = 3 V**

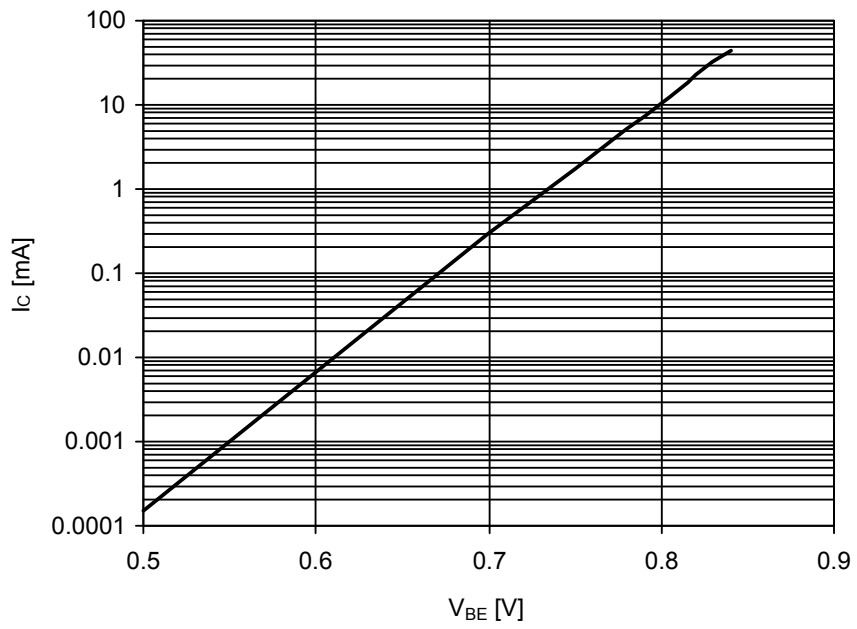

Figure 5 **Collector current vs. base emitter voltage $I_C = f(V_{BE})$, $V_{CE} = 2$ V**

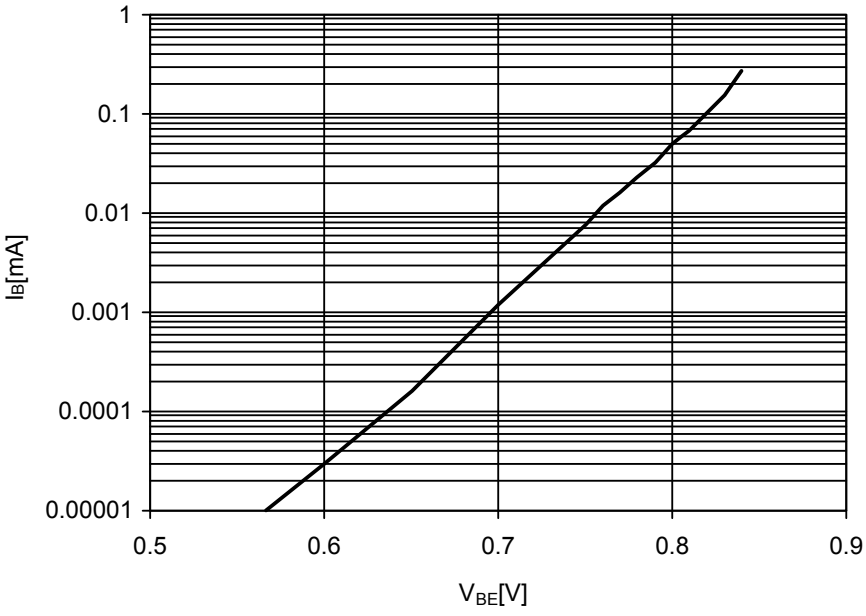

Figure 6 **Base current vs. base emitter forward voltage $I_B = f(V_{BE})$, $V_{CE} = 2$ V**

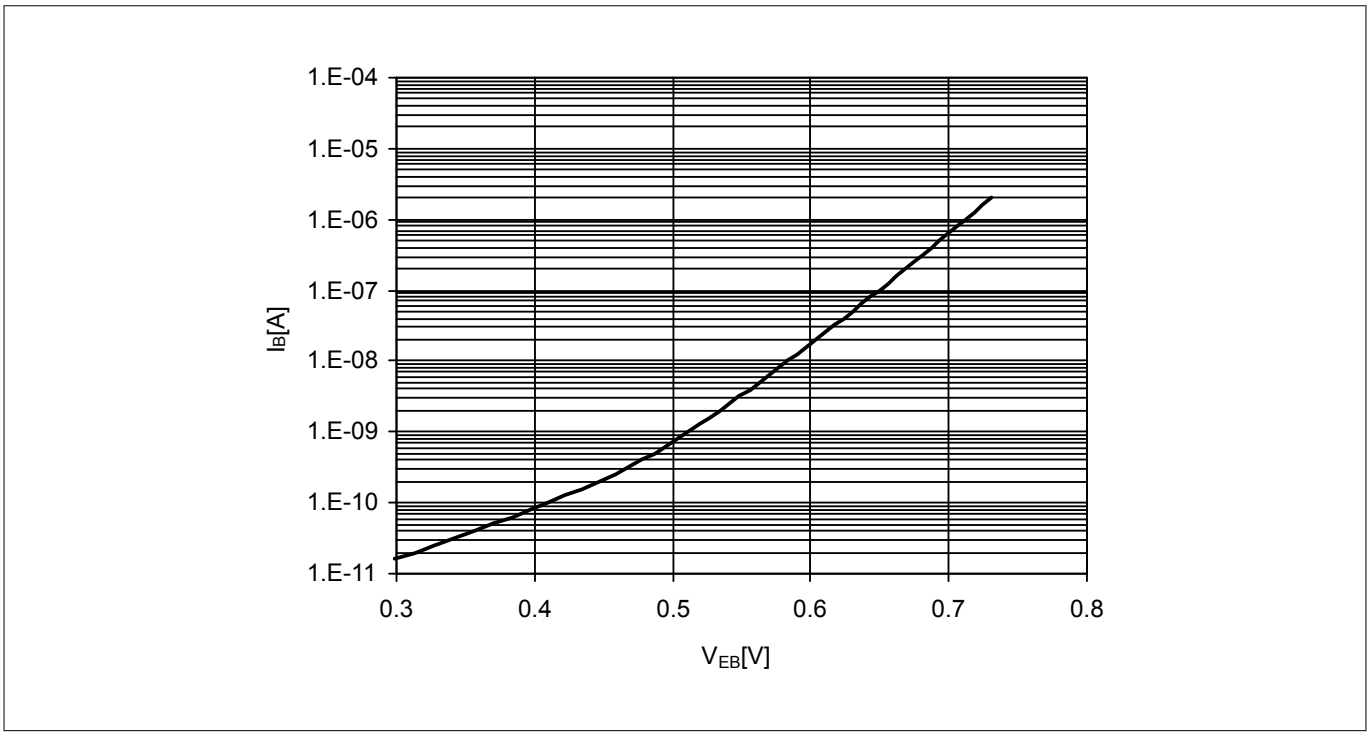

Figure 7 **Base current vs. base emitter reverse voltage $I_B = f(V_{EB})$, $V_{CE} = 2$ V**

3.5 Characteristic AC diagrams

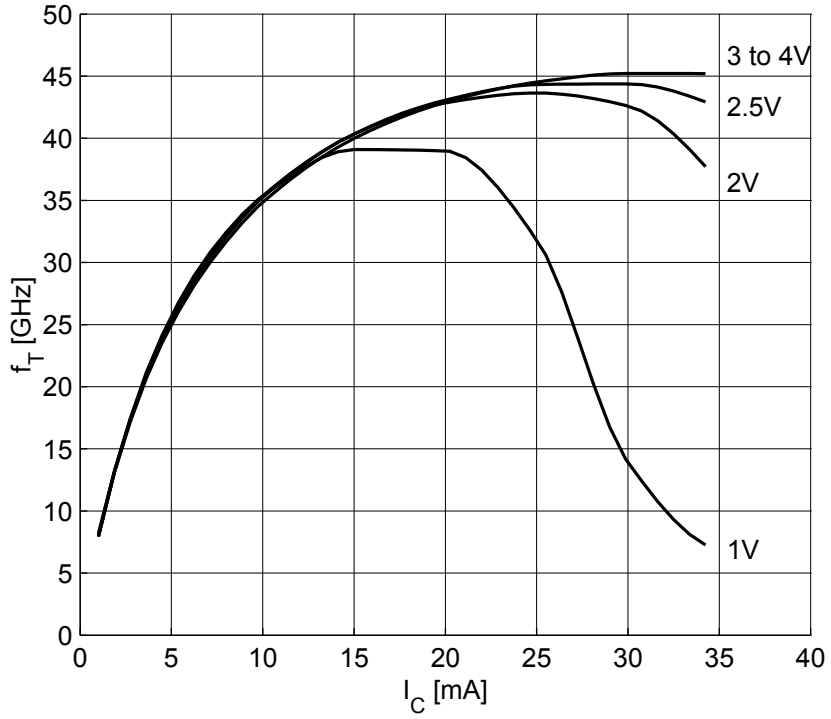

Figure 8 **Transition frequency $f_T = f(I_C)$, $f = 2$ GHz, V_{CE} = parameter**

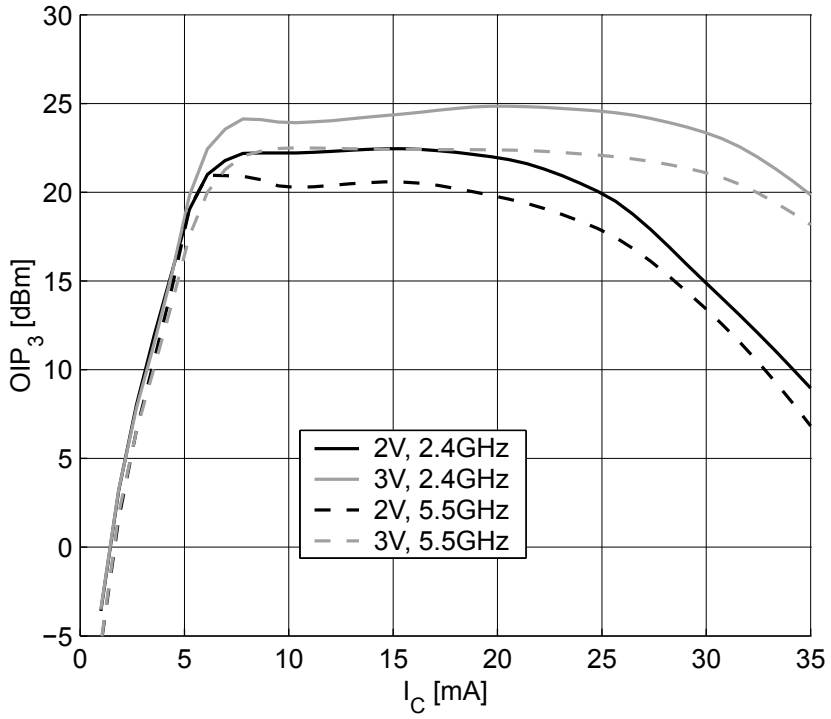

Figure 9 **3rd order intercept point $OIP_3 = f(I_C)$, $Z_S = Z_L = 50\ \Omega$, V_{CE}, f = parameters**

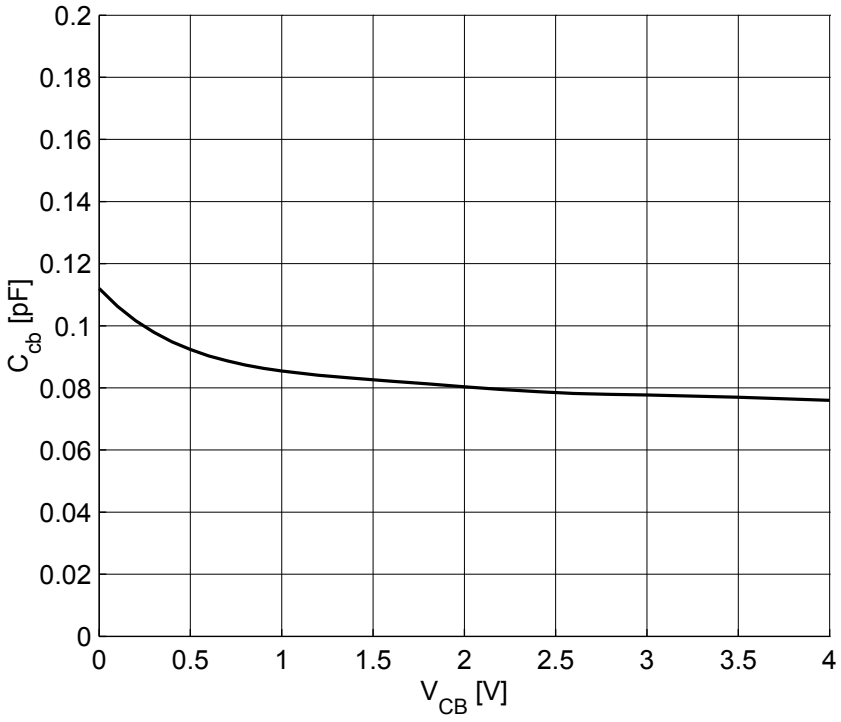

Figure 10 **Collector base capacitance $C_{CB} = f(V_{CB})$, $f = 1$ MHz**

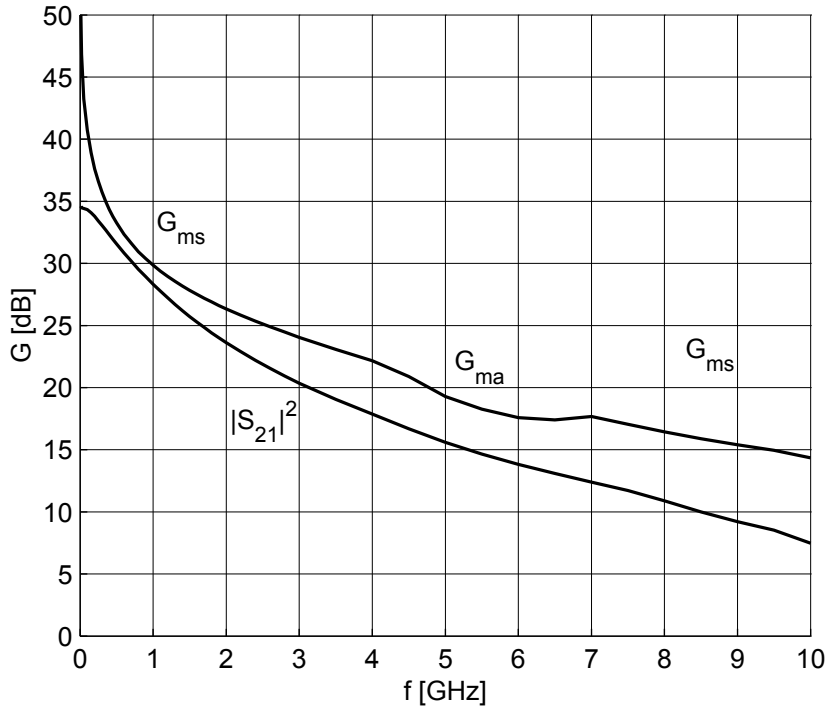

Figure 11 **Gain G_{ma}, G_{ms}, $|S_{21}|^2 = f(f)$, $V_{CE} = 3$ V, $I_C = 25$ mA**

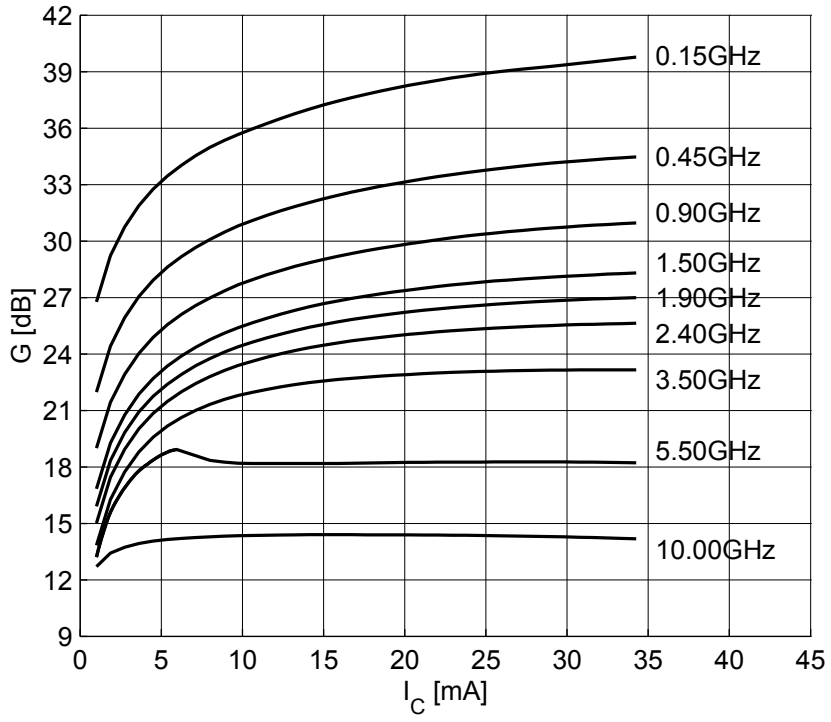

Figure 12 **Maximum power gain G_{max} = f(I_C), V_{CE} = 3 V, f = parameter in GHz**

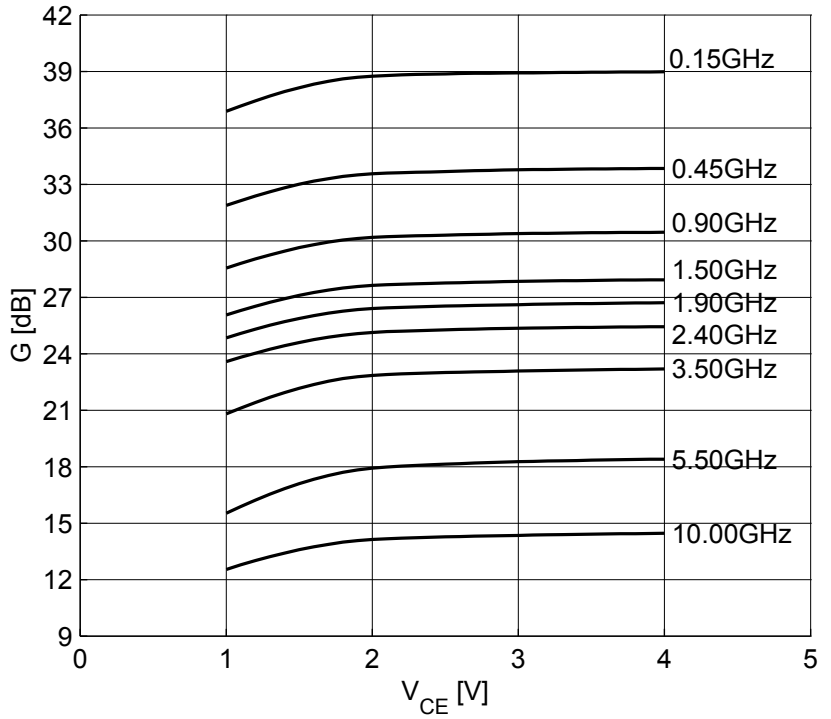

Figure 13 **Maximum power gain G_{max} = f(V_{CE}), I_C = 25 mA, f = parameter in GHz**

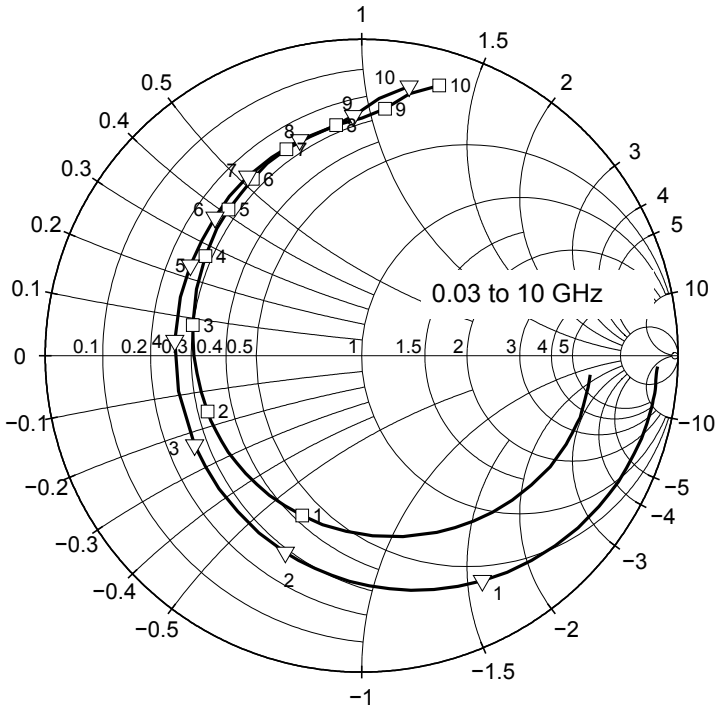

Figure 14 **Input reflection coefficient S_{11} = f(f), V_{CE} = 3 V, I_C = 6 / 25 mA**

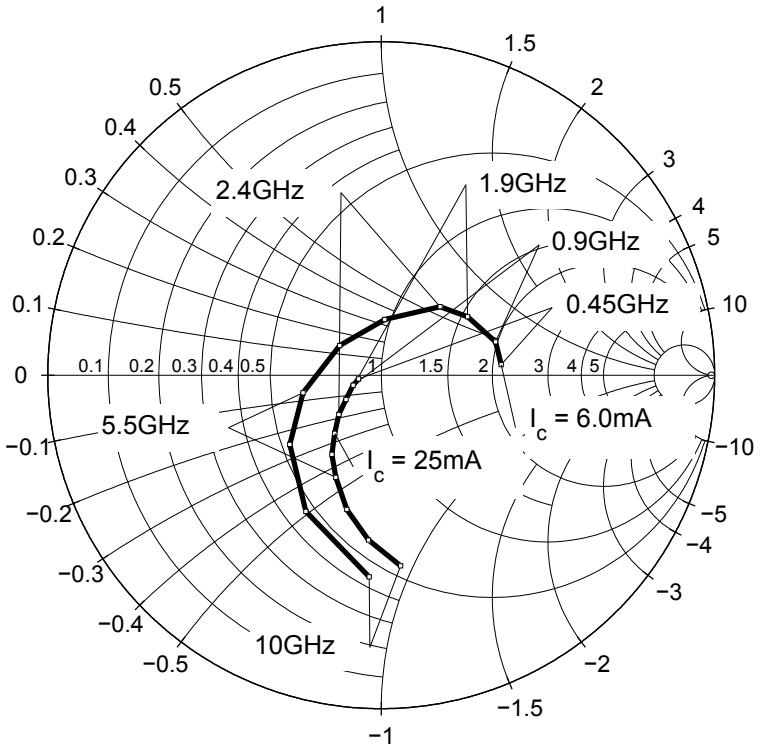

Figure 15 **Source impedance for minimum noise figure Z_{opt} = f(f), V_{CE} = 3 V, I_C = 6 / 25 mA**

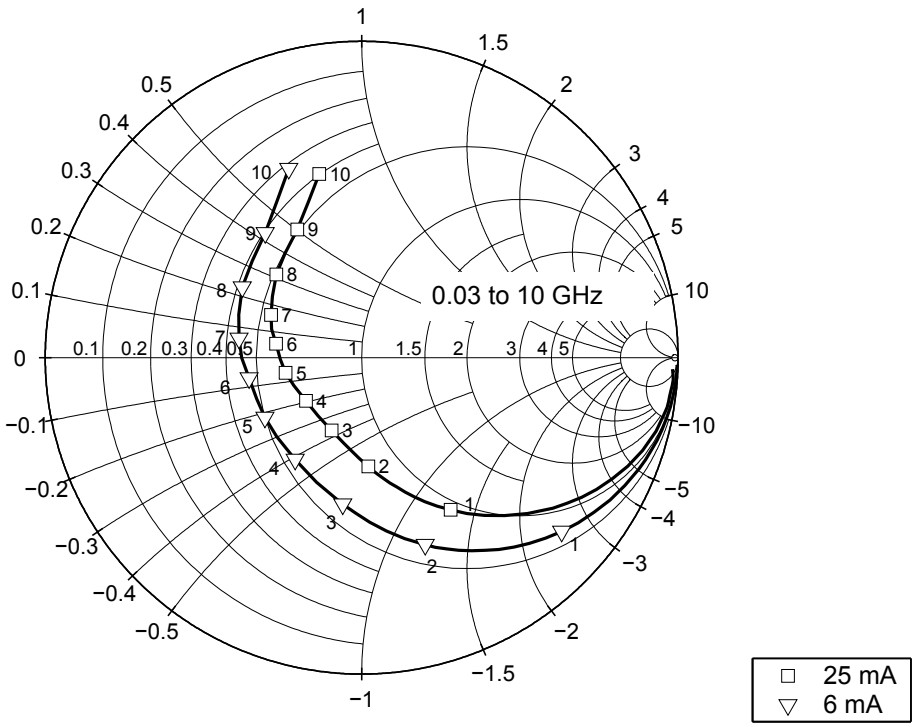

Figure 16 **Output reflection coefficient S_{22} = f(f), V_{CE} = 3 V, I_C = 6 / 25 mA**

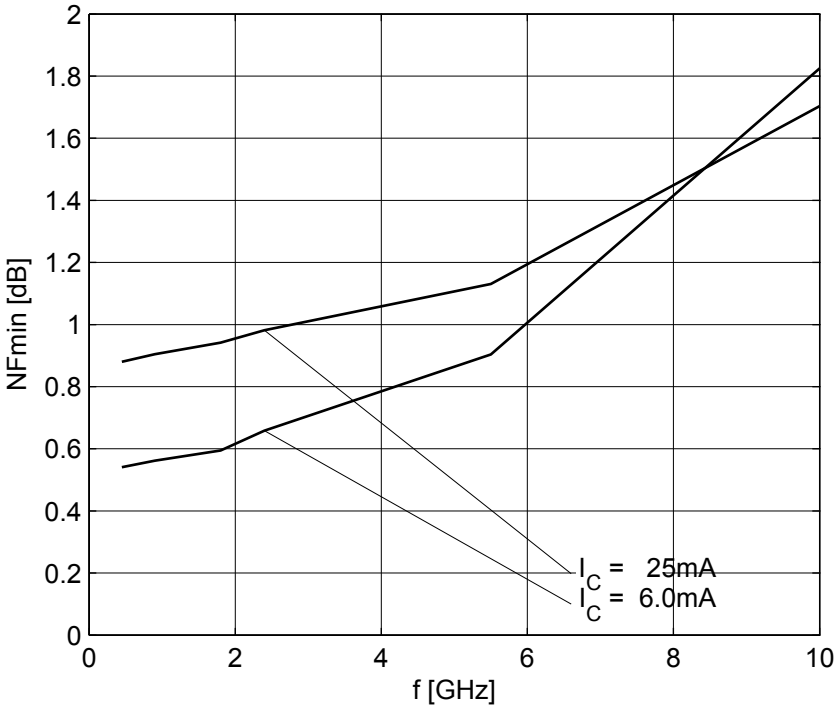

Figure 17 **Noise figure NF_{min} = f(f), V_{CE} = 3 V, Z_S = $Z_{S,opt}$, I_C = 6 / 25 mA**

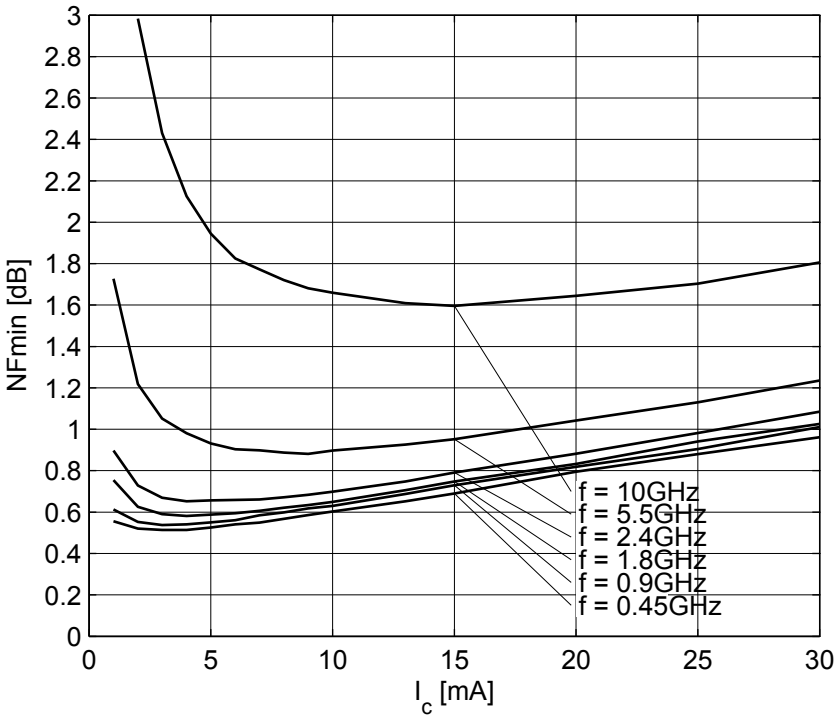

Figure 18 **Noise figure NF_{min} = f(I_C), V_{CE} = 3 V, Z_S = $Z_{S,opt}$, f = parameter in GHz**

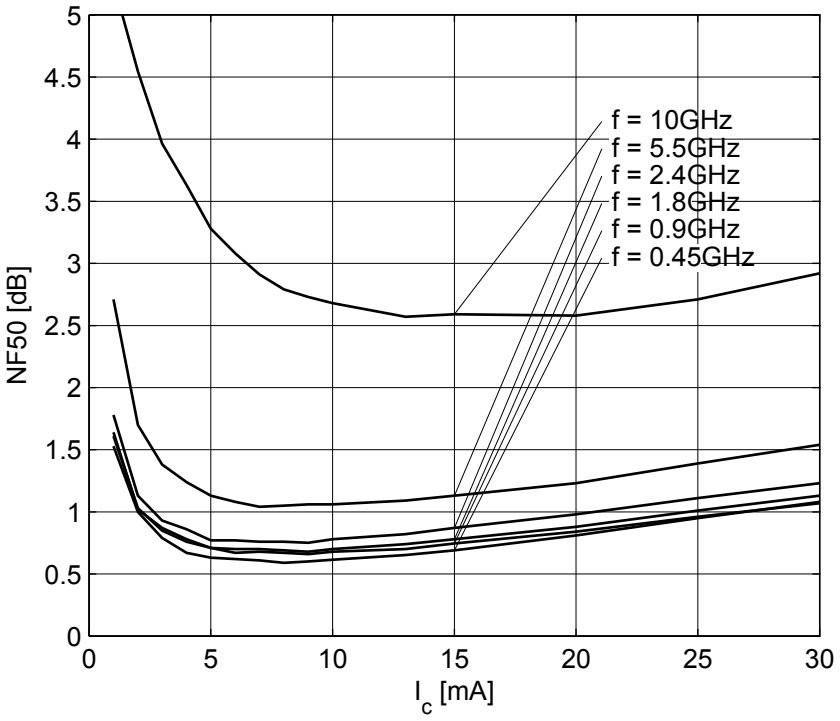

Figure 19 **Noise figure NF_{50} = f(I_C), V_{CE} = 3 V, Z_S = 50 Ω, f = parameter in GHz**

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves. T_A = 25 °C.

4 Package information SOT343

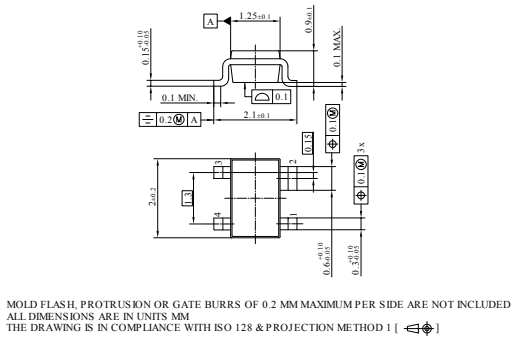

Figure 20 Package outline

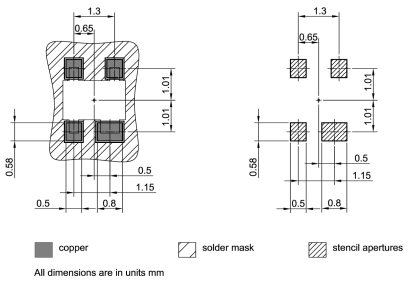

Figure 21 Foot print

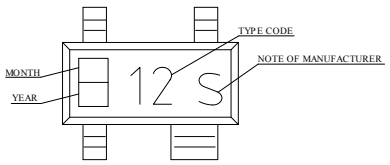

Figure 22 Marking layout example

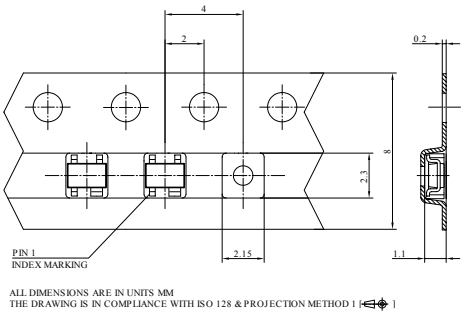

Figure 23 Tape dimensions

Revision history

Document version	Date of release	Description of changes
2.0	2018-09-26	New datasheet layout.

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